IEC 61837-2

Edition 3.1 2020-09
CONSOLIDATED VERSION

FINAL VERSION

VERSION FINALE

Surface mounted piezoelectric devices for frequency control and selection – Standard outlines and terminal lead connections –

Part 2: Ceramic enclosures

Dispositifs piézoélectriques à montage en surface pour la commande et le choix de la fréquence – Encombrements normalisés et connexions des sorties –

Partie 2: Enveloppes en céramique

IEC 61837-2:2018-05+AMD1:2020-09 CSV (en-fr)

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

SURFACE MOUNTED PIEZOELECTRIC DEVICES FOR FREQUENCY CONTROL AND SELECTION – STANDARD OUTLINES AND TERMINAL LEAD CONNECTIONS –

Part 2: Ceramic enclosures

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This consolidated version of the official IEC Standard and its amendment has been prepared for user convenience.

IEC 61837-2 edition 3.1 contains the third edition (2018-05) [documents 49/1252/CDV and 49/1276/RVC] and its amendment 1 (2020-09) [documents 49/1338/CDV and 49/1347/RVC].

This Final version does not show where the technical content is modified by amendment 1. A separate Redline version with all changes highlighted is available in this publication.

International Standard IEC 61837-2 has been prepared by IEC technical committee 49: Piezoelectric, dielectric and electrostatic devices and associated materials for frequency control, selection and detection.

This third edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

a) revision of the figures to match the notation of the drawings of IEC 61240:2016;

b) addition of 7 enclosures as follows: DCC-6/5032A, DCC-6/3225A, DCC-4/3215C, DCC-6/2016A, DCC-2/2012C, DCC-2/1610C, DCC-4/1210C.

As a result, this third edition contains a total of 45 enclosure types, which are listed in Table 1.

This International Standard is to be read in conjunction with IEC 61240:2016.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 61837 series, published under the general title *Surface mounted piezoelectric devices for frequency control and selection – Standard outlines and terminal lead connections* , can be found on the IEC website.

The committee has decided that the contents of the base publication and its amendment will remain unchanged until the stability date indicated on the IEC web site under "http://webstore.iec.ch" in the data related to the specific publication. At this date, the publication will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

SURFACE MOUNTED PIEZOELECTRIC DEVICES FOR FREQUENCY CONTROL AND SELECTION – STANDARD OUTLINES AND TERMINAL LEAD CONNECTIONS –

Part 2: Ceramic enclosures

1 Scope

This part of IEC 61837 deals with standard outlines and terminal lead connections as they apply to surface-mounted devices (SMD) for frequency control and selection in ceramic enclosures, and is based on IEC 61240:2016.

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 61240:2016, *Piezoelectric devices – Preparation of outline drawings of surface-mounted devices (SMD) for frequency control and selection – General rules*

3 Terms and definitions

No terms and definitions are listed in this document.

ISO and IEC maintain terminological databases for use in standardization at the following addresses:

- IEC Electropedia: available at http://www.electropedia.org/
- ISO Online browsing platform: available at http://www.iso.org/obp

4 Configuration of enclosures

The enclosures of the surface-mounted devices are made of ceramic materials with the terminals of deposited metal film (leadless type) based on a descriptive designation system for semiconductors – devices packages.

The configuration symbols are shown as follows:

a) DCC (dual chip carrier);
b) QCC (quad chip carrier).

5 Designation of types

The designation of types is shown on four parts as follows: